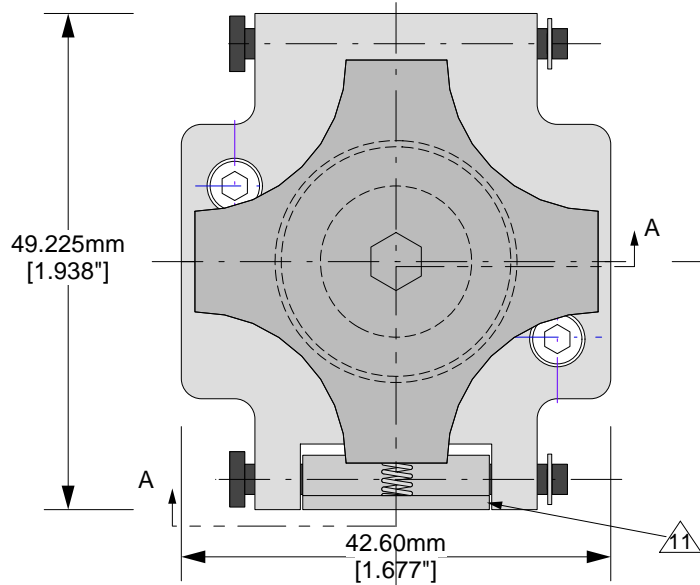
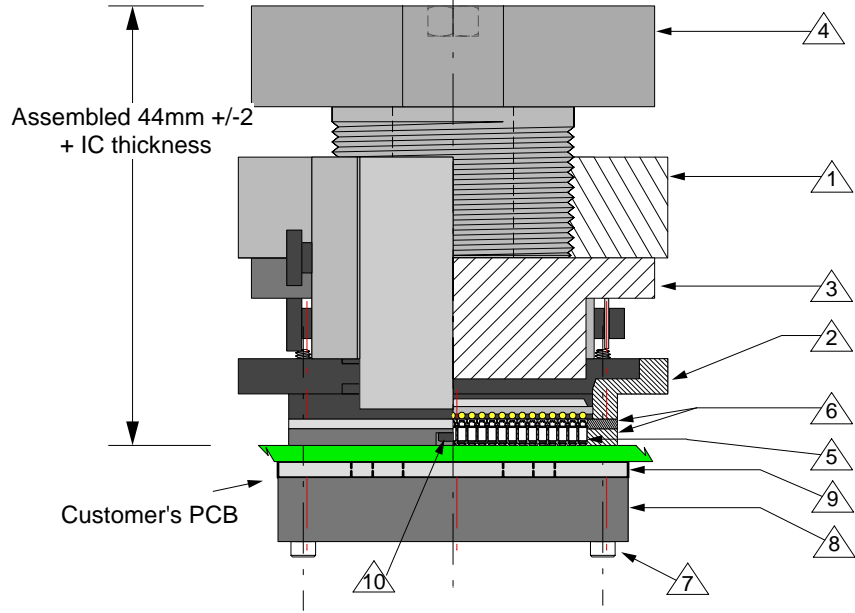


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

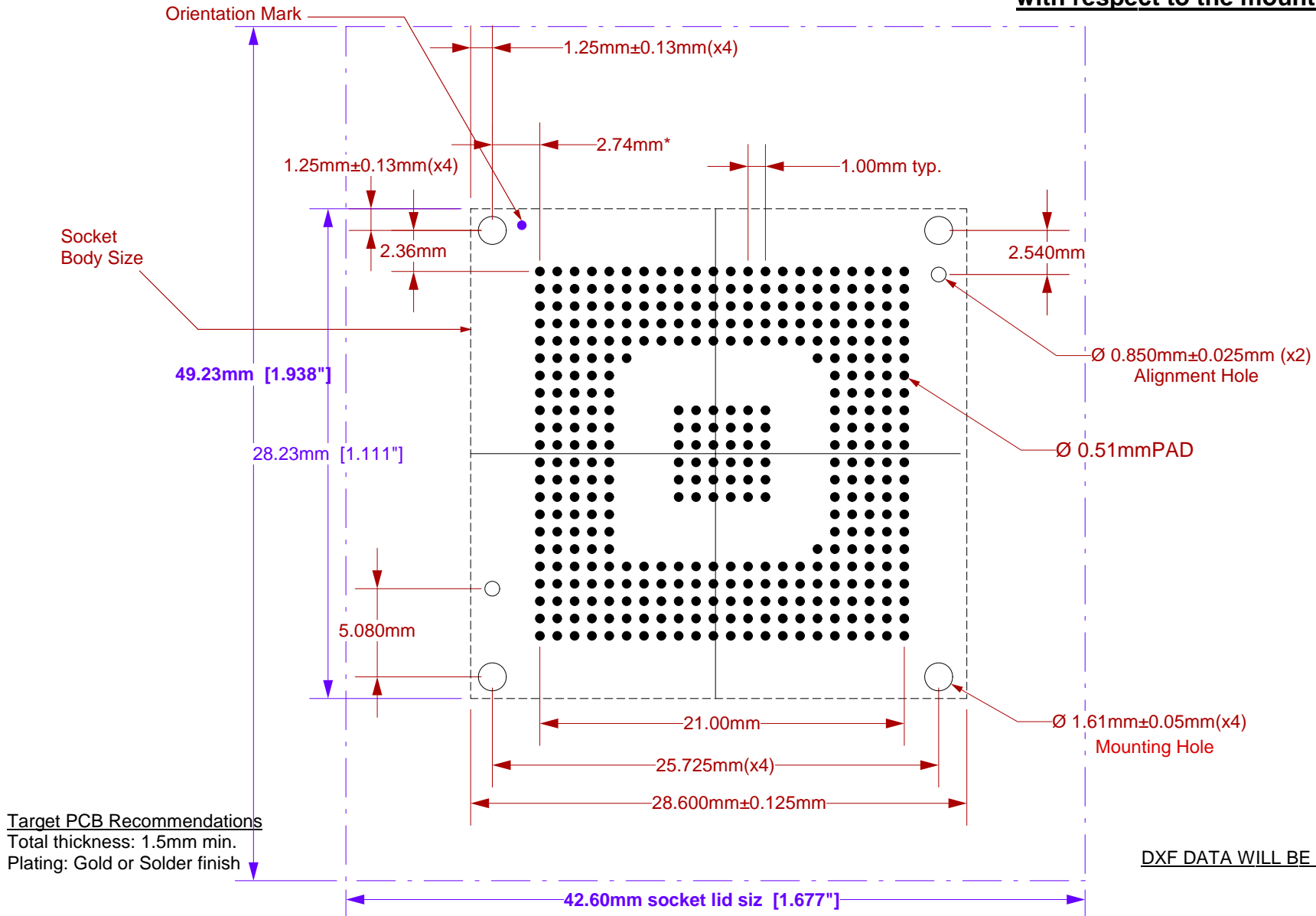
- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
- 5 Pogo Pin:
Plungers - Hardened Steel/ Gold plated
Barrel - Copper Alloy/ Gold plated
Spring - Stainless Steel/ Gold wire
- 6 Pogo Pin Guides: Ultem 1000.
- 7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- 11 Latch: Black anodized Aluminum.

	SS-BGA379C-01 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 2/28/07	
		File: SS-BGA379C-01 Dwg	Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

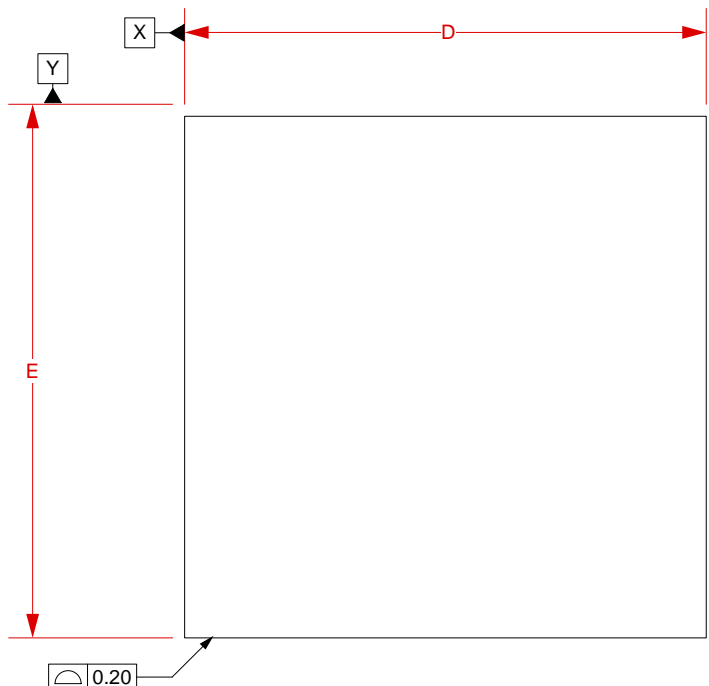
***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



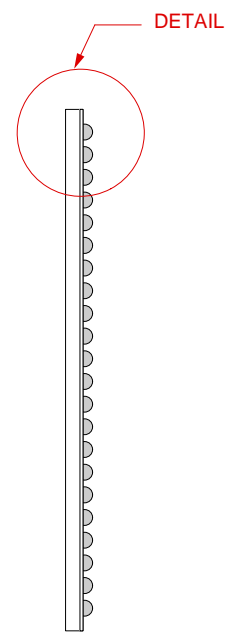
DXF DATA WILL BE PROVIDED

Recommended PCB Layout
Tolerances: ±0.025mm [±0.001"]
unless stated otherwise.

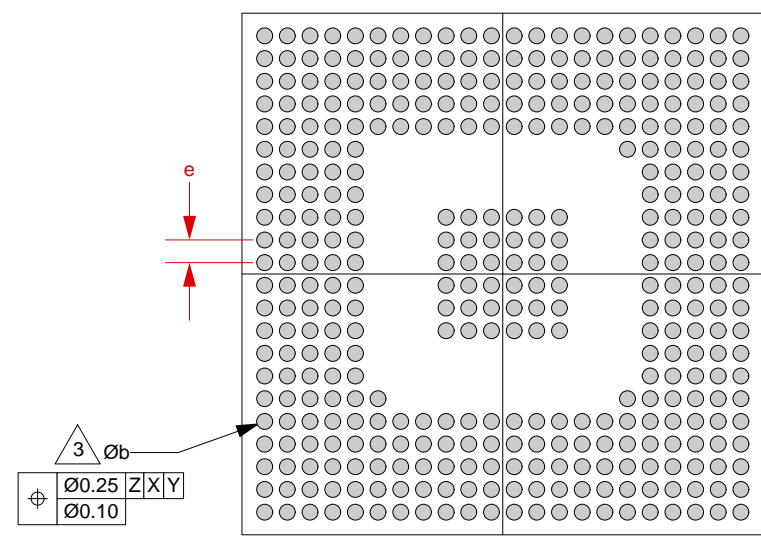
<p>SS-BGA379C-01 Drawing</p>	<p>Status: Released</p>	<p>Scale: 3:1</p>	<p>Rev: A</p>
<p>© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>Drawing: J. Glab</p>	<p>Date: 2/28/07</p>	
<p>File: SS-BGA379C-01 Dwg</p>		<p>Modified:</p>	



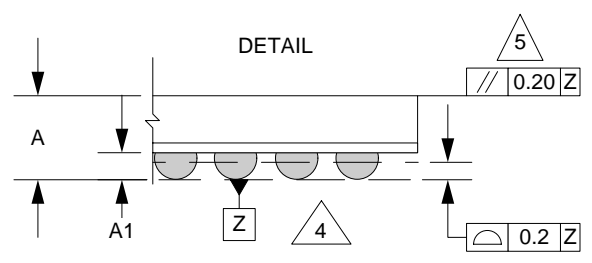
TOP VIEW



SIDE VIEW




BOTTOM VIEW



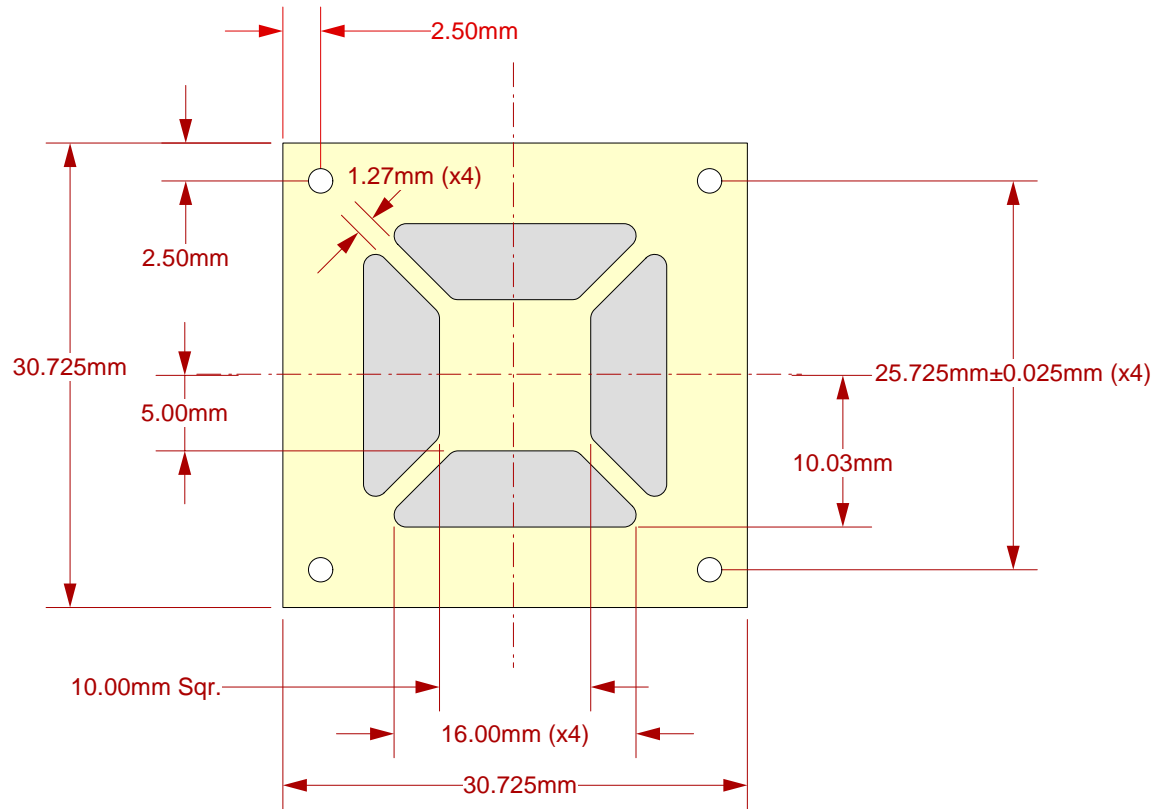
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- $\triangle 3$ Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - $\triangle 4$ Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - $\triangle 5$ Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.43
A1	0.4	0.6
b		0.7
D	23.00 BSC	
E	23.00 BSC	
e	1.0 BSC	

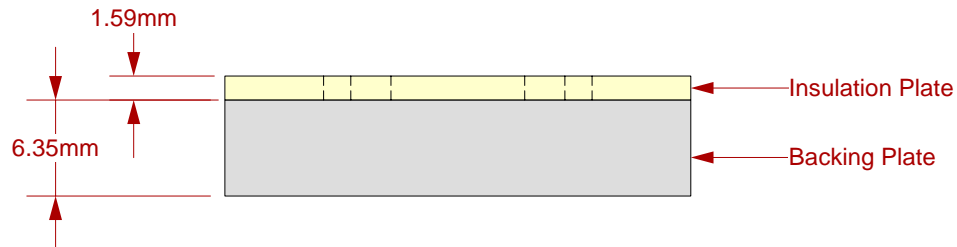
22x22 Array

 <p>© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SS-BGA379C-01 Drawing</p>	<p>Status: Released</p>	<p>Scale:</p>	<p>Rev: A</p>
	<p>Drawing: J. Glab</p>	<p>Date: 2/28/07</p>		
	<p>File: SS-BGA379C-01 Dwg</p>	<p>Modified:</p>		


Top View



Side View



Description: Backing Plate with Insulation Plate

	SS-BGA379C-01 Drawing	Status: Released	Scale:	Rev: A
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		File: SS-BGA379C-01 Dwg	Modified:	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)